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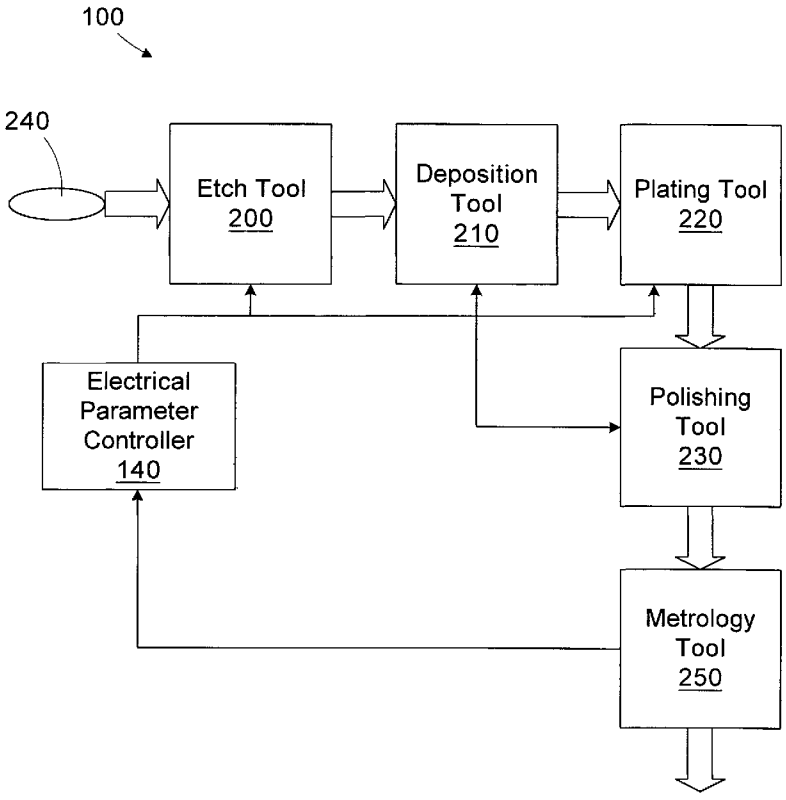
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(54) Title: METHOD AND APPARATUS FOR CONTROLLING A FABRICATION PROCESS BASED ON A MEASURED ELECTRICAL CHARACTERISTIC



(57) Abstract: A method includes performing at least one process for forming a feature of a semiconductor device in accordance with an operating recipe. An electrical performance characteristic of the feature is measured. The measured electrical performance characteristic is compared to a target value for the electrical performance characteristic. At least one parameter of the operating recipe is determined based on the comparison. A system (10, 100) includes a process tool (30-80, 200, 210, 220, 230), a metrology tool (30-80, 250), and a controller (140). The process tool (30-80, 200, 210, 220, 230) is configured to perform at least one process for forming a feature of a semiconductor device in accordance with an operating recipe. The metrology tool (30-80, 250) is configured to measure an electrical performance characteristic of the feature. The controller (140) is configured to compare the measured electrical performance characteristic to a target value for the electrical performance characteristic and determine at least one parameter of the operating recipe based on the comparison.

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